



# Navitas

*Let's go* **GaNFast™**

**GaN Power IC Enable 4x Power Density 150W AC/DC Converter Design**

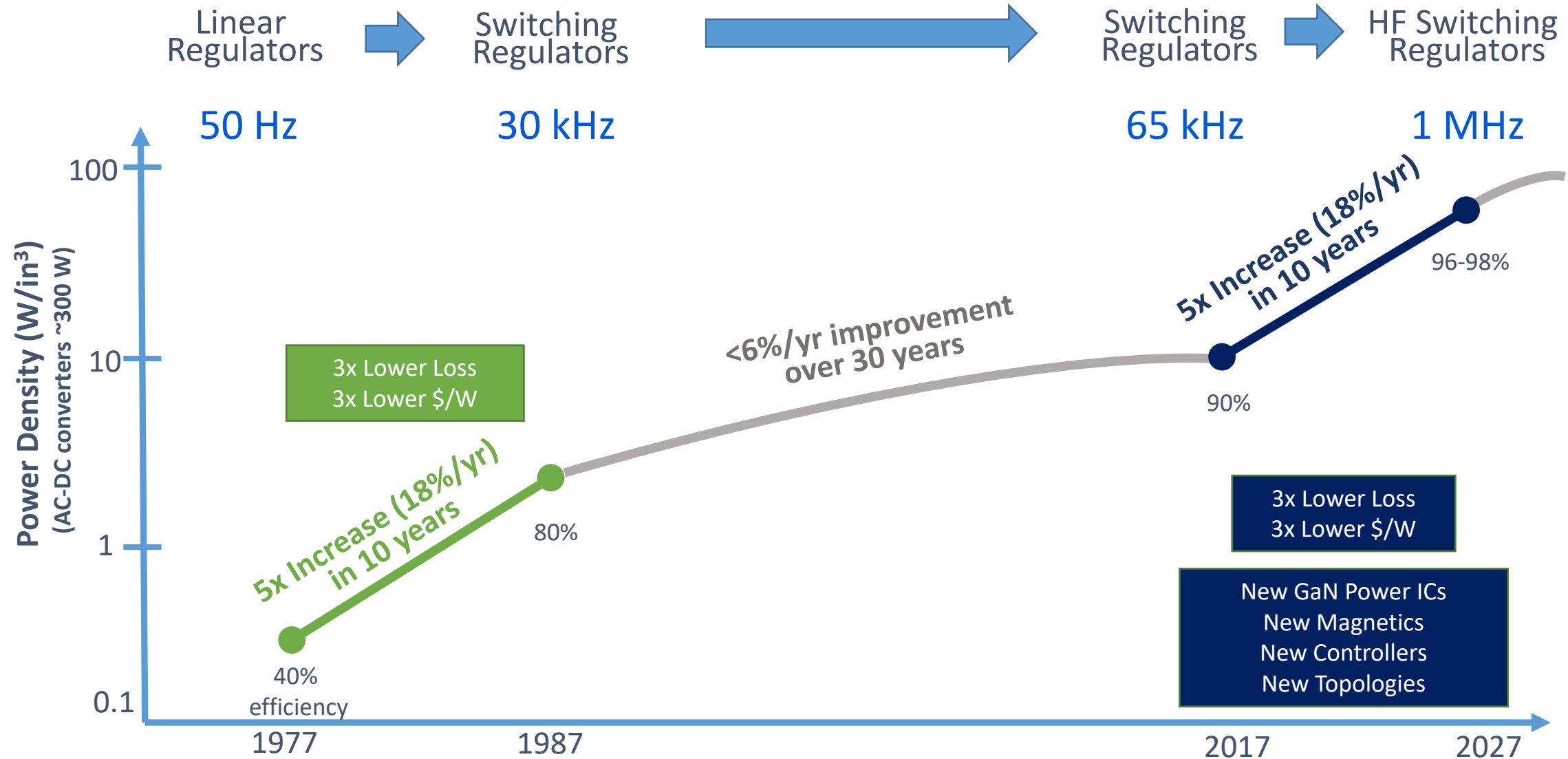
IEEE PEAC 2018 Industry Session: "Power Devices and Applications" November 6<sup>th</sup>, 2018

Peter Huang, Director of Technical Marketing and Field Application

[peter.huang@navitassemi.com](mailto:peter.huang@navitassemi.com)



# A Power Supply Revolution Once Again! GaNFast™







# The Power of GaN Power ICs

... Unequaled Integration, Speed & Efficiency



**Driver Circuits**

**Power Devices**

**Passive Components**

**Switching Frequency**

**Energy Efficiency**

*Silicon*



85-90%

*Discrete GaN*



88-92%

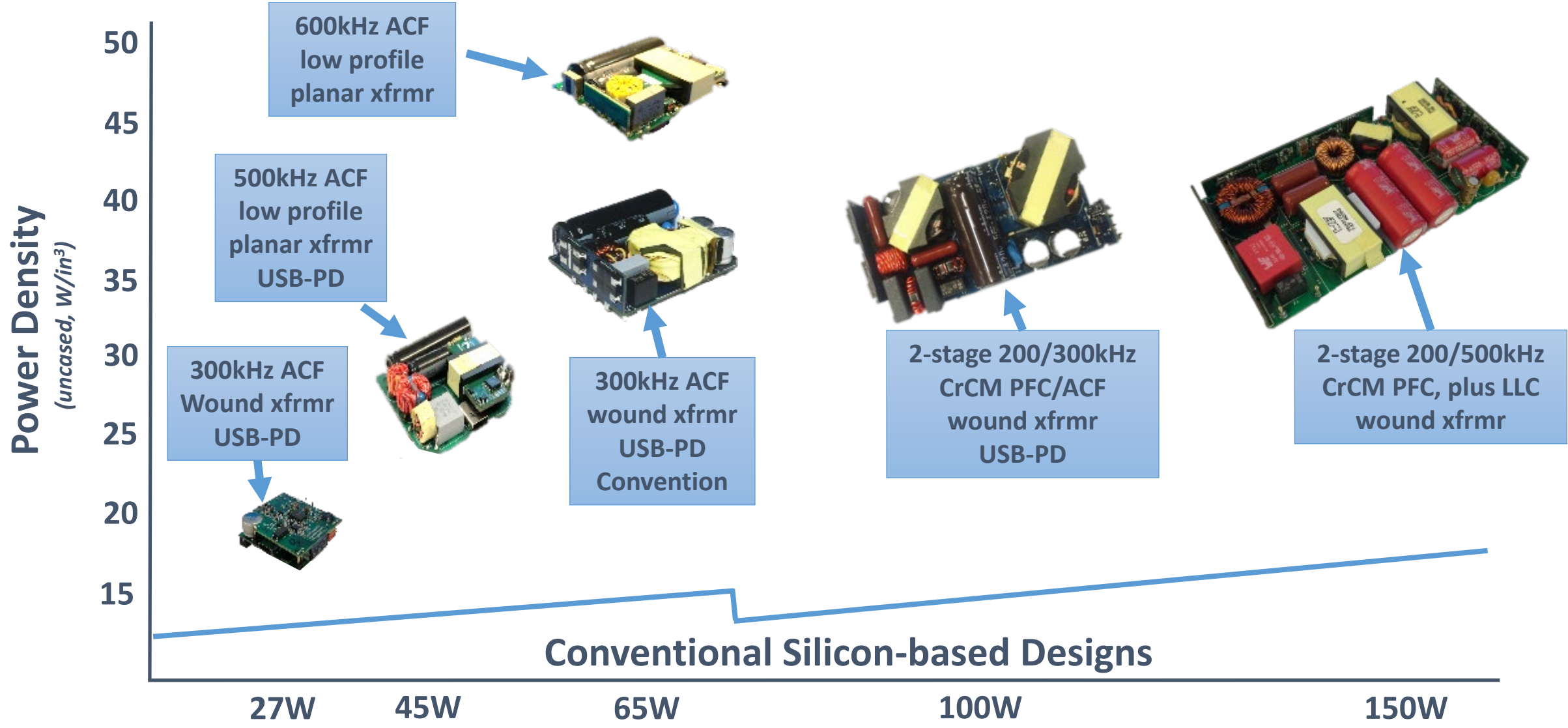
*GaN Power ICs*



90-95%

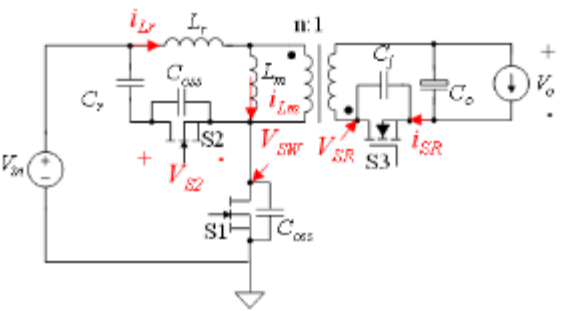


# The New World of GaNFast™ Adapters





# Key Elements For High-Density Adaptor



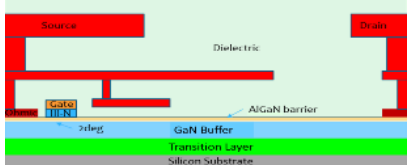
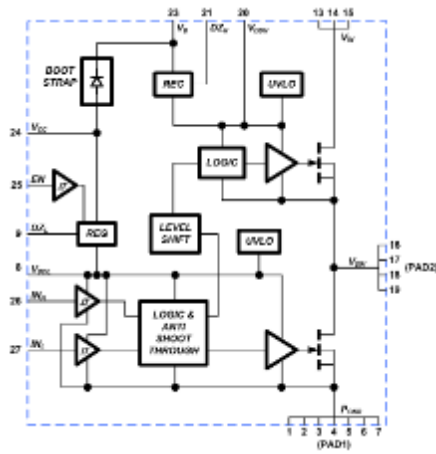
**New Topologies**

**Higher Integration**

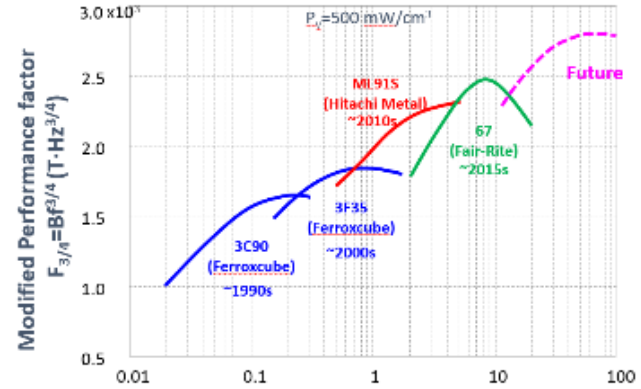
**GaN Device**

**Hi-Frequency Controllers**

**Hi-Frequency Magnetic**

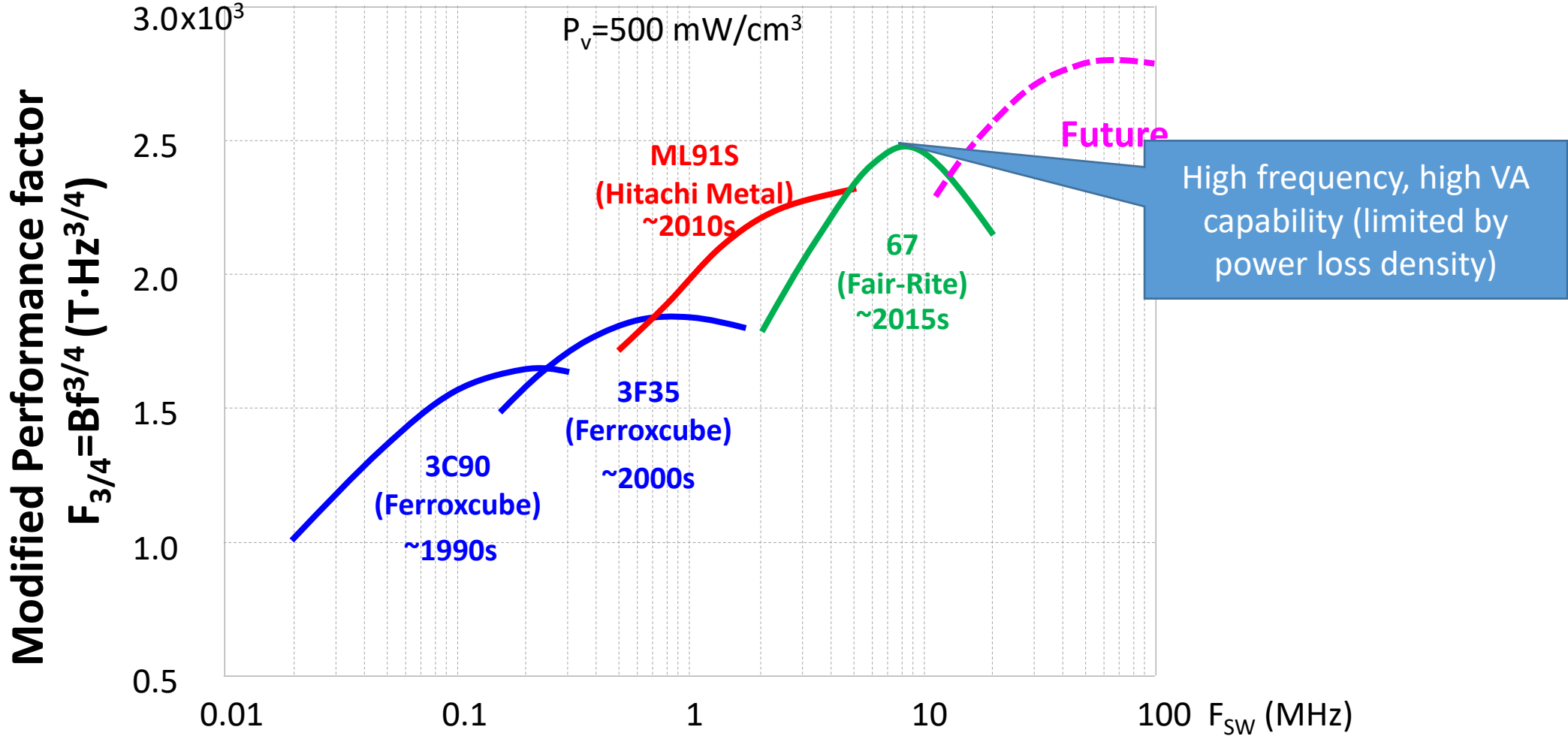


>500Khz Controllers are ready!





# Magnetics Frequencies – 10x Every Decade



Y. Han, G. Cheung, A. Li, C. R. Sullivan and D. J. Perreault, "Evaluation of Magnetic Materials for Very High Frequency Power Applications," in *IEEE Transactions on Power Electronics*, vol. 27, no. 1, pp. 425-435, Jan. 2012.

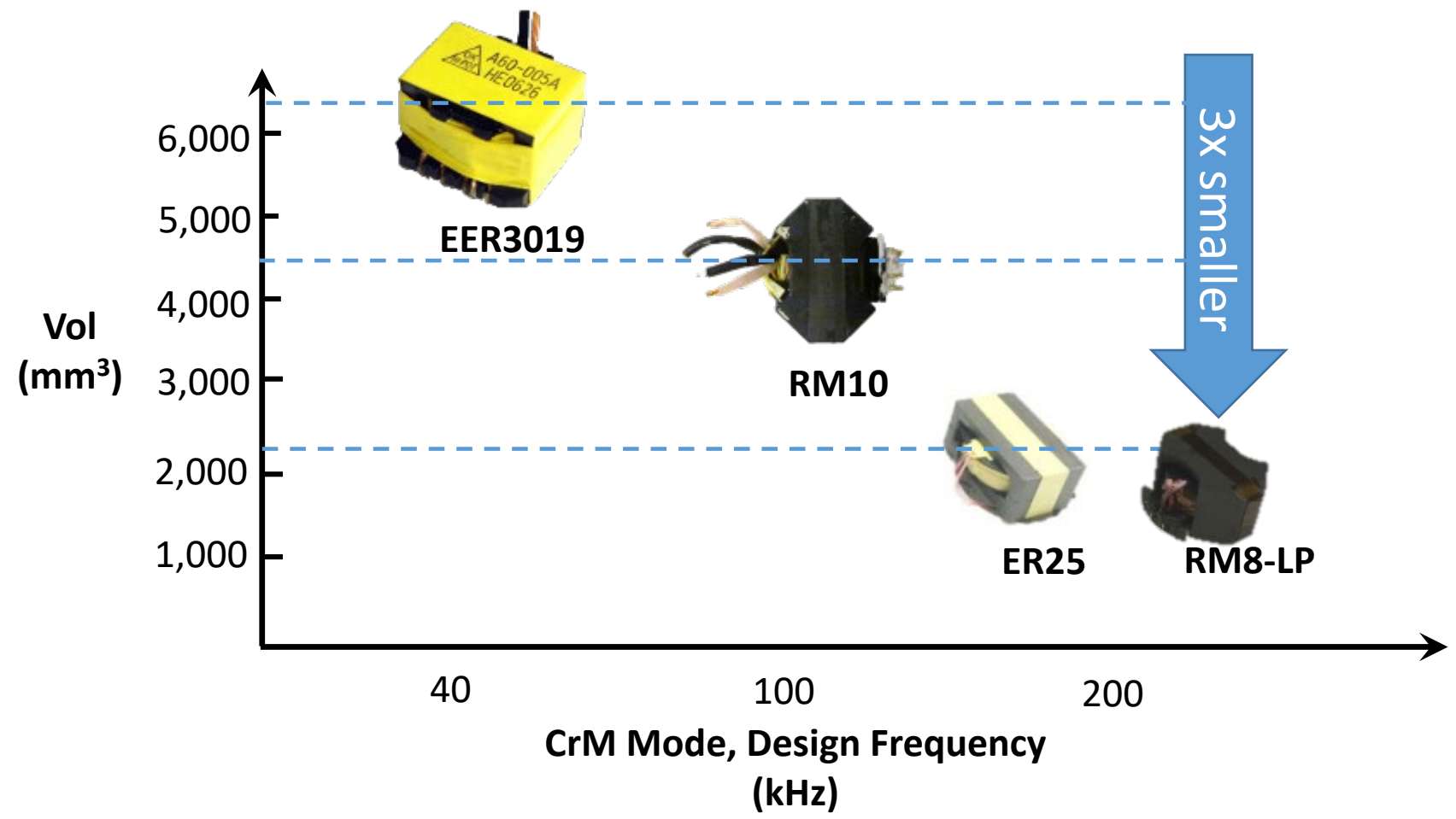
A. J. Hanson, J. A. Belk, S. Lim, C. R. Sullivan and D. J. Perreault, "Measurements and Performance Factor Comparisons of Magnetic Materials at High Frequency," in *IEEE Transactions on Power Electronics*, vol. 31, no. 11, pp. 7909-7925, Nov. 2016.





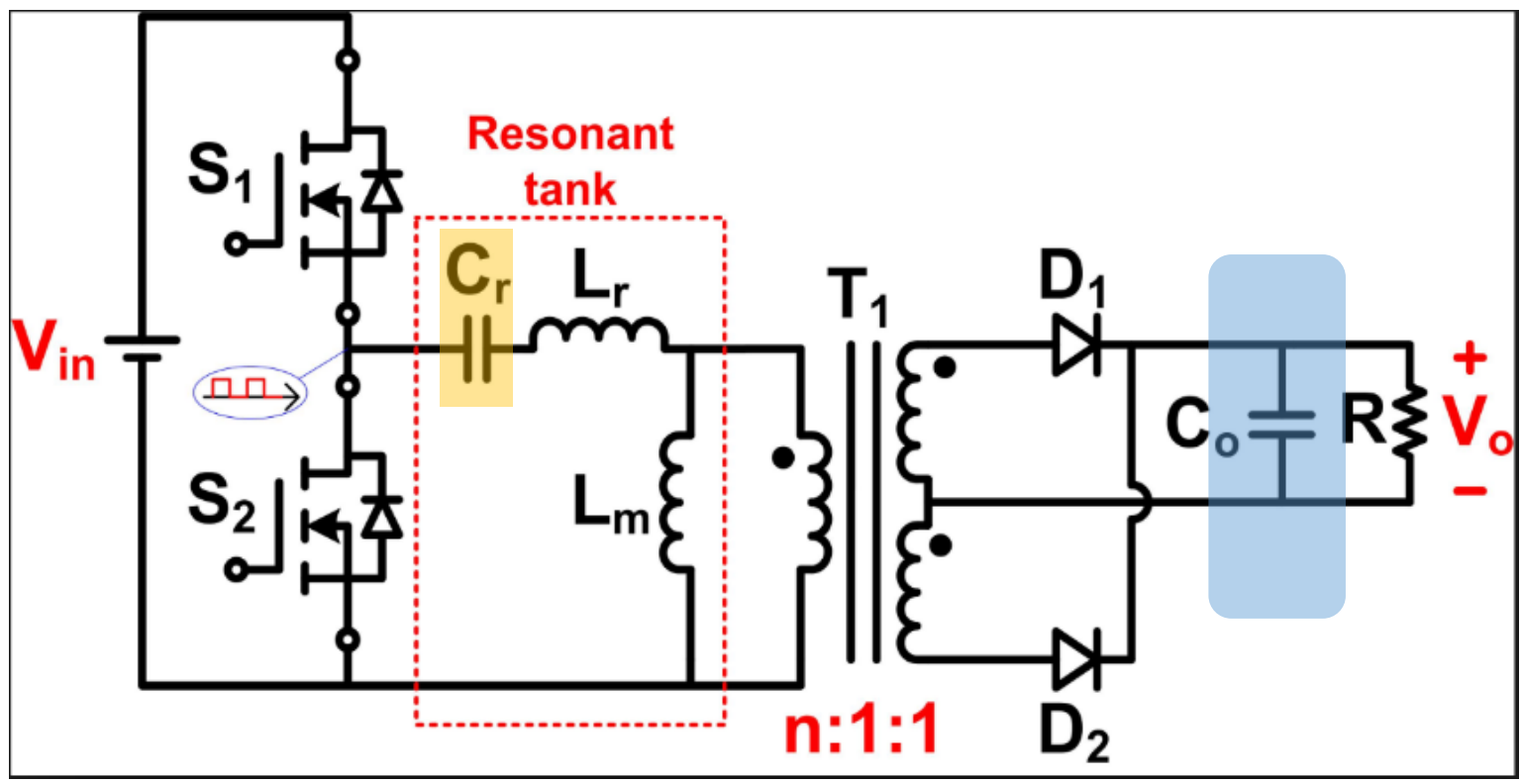
# Speed Reduces Size: Magnetics

## 150W PFC Boost Inductor (Lm)





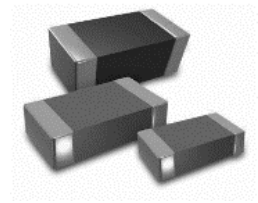
# Speed Reduces Size: Capacitors



100kHz



500kHz

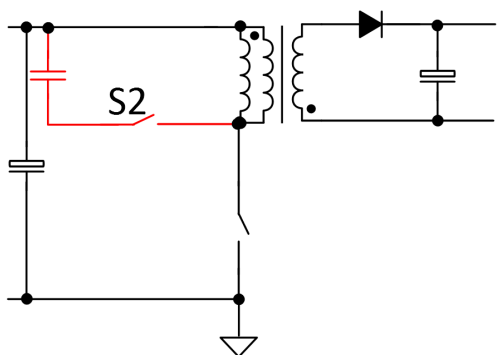






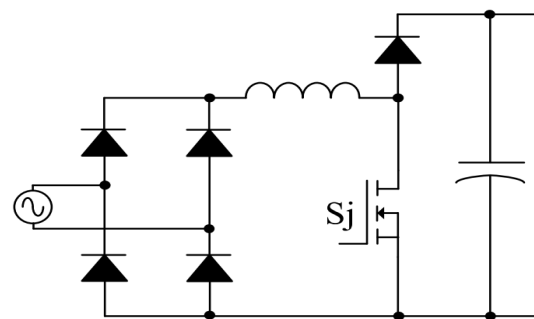
# High Frequency Topologies

## Active Clamp Flyback



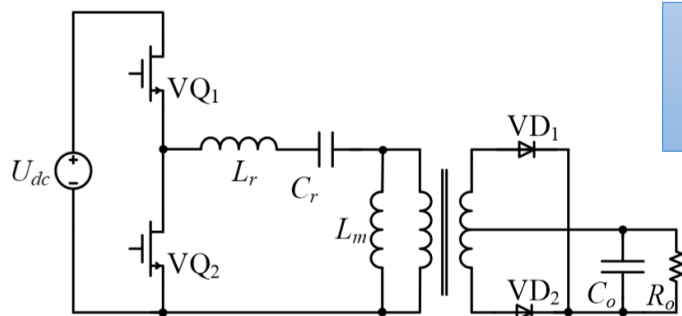
>1MHz(GaN)  
Soft-switching

## Bridge CrM Boost PFC



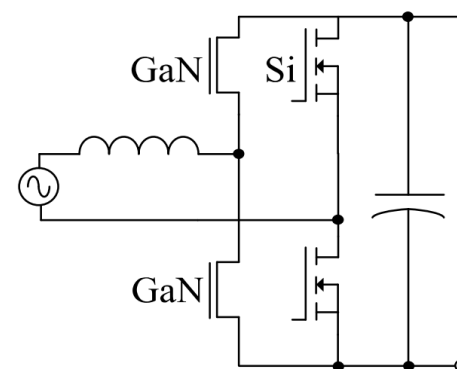
>200kHz  
Quasi-Resonant

## LLC



>1MHz(GaN)  
Soft-switching

## Bridgeless CrM Totem Pole PFC

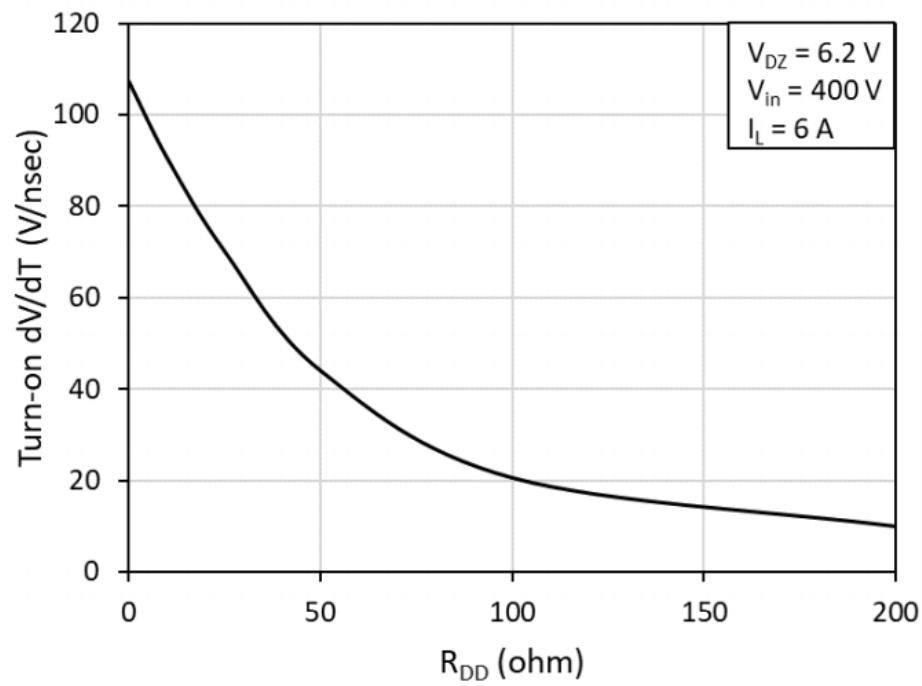
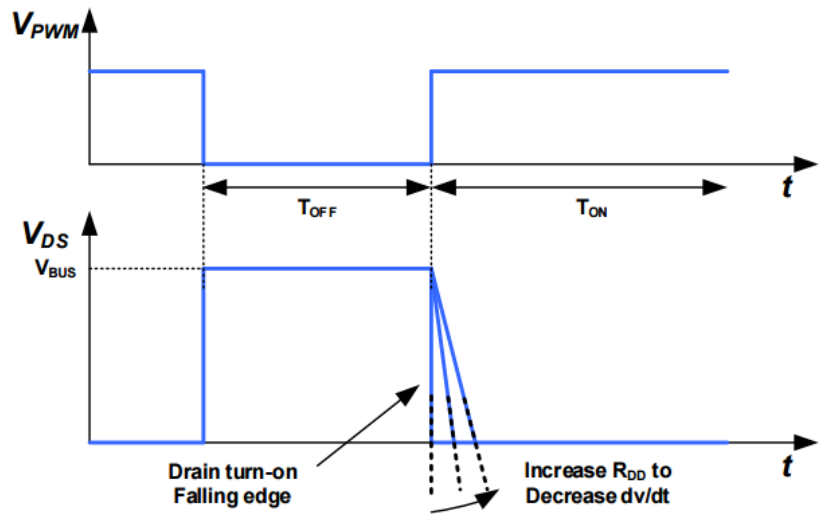
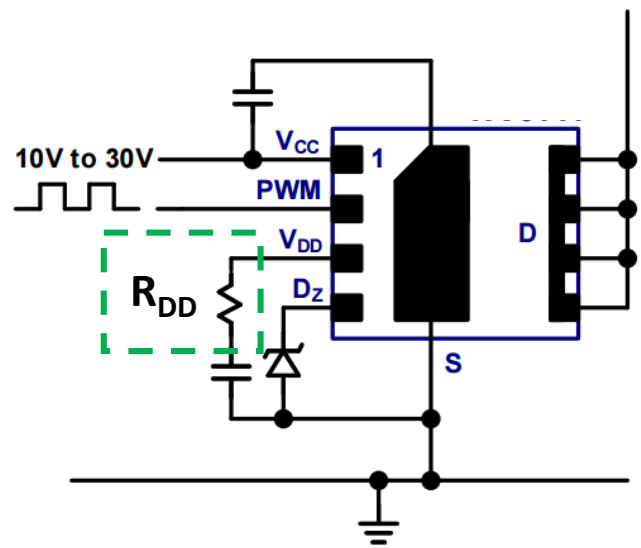


>1MHz(GaN) with  
Soft-switching





# Voltage Slew-Rate Control... Easy EMI Tuning



$dV/dt$  controllable from 100 V/ns to 10 V/ns





# Speed & Integration → Eliminate $T_{off}$ Losses

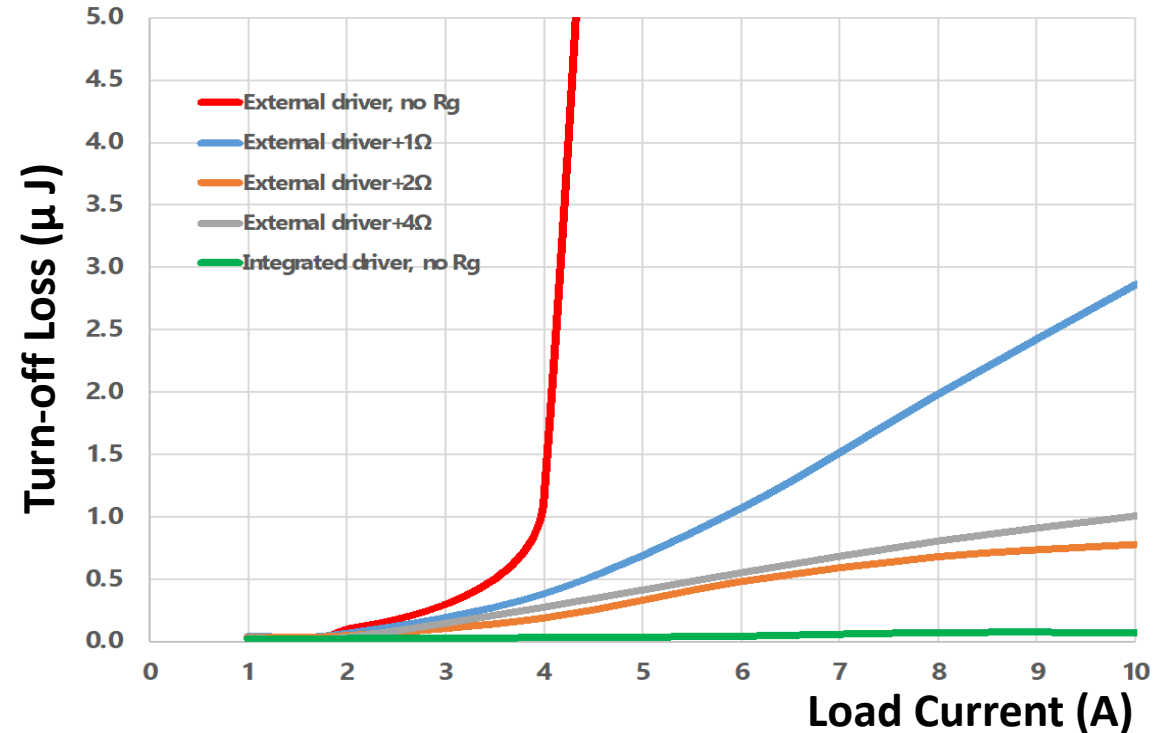


## External drivers

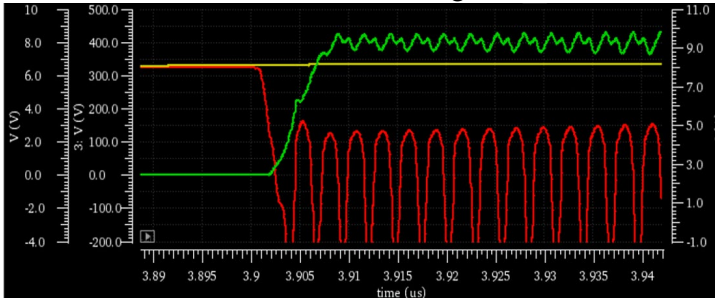
- Just 1-2 nH of gate loop inductance can cause unintended turn-on
- Gate resistors reduce spikes but create additional losses

## Integrated GaN drivers (iDrive™)

- Eliminate the problem
- Negligible turn-off losses
- Removes unintended turn-on due to high  $dV/dt$



Discrete FET and drive, no R<sub>G</sub> = out of control



Discrete FET and drive, with R<sub>G</sub> = slow, lossy



Integrated FET and drive, no R<sub>G</sub> = fast, efficient

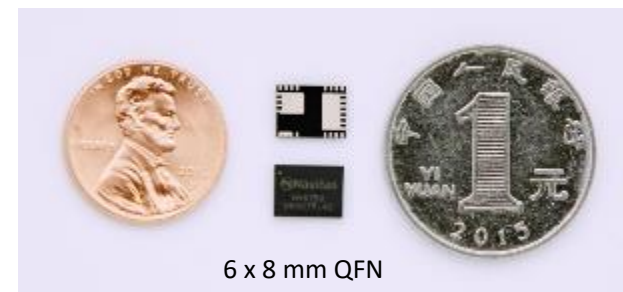
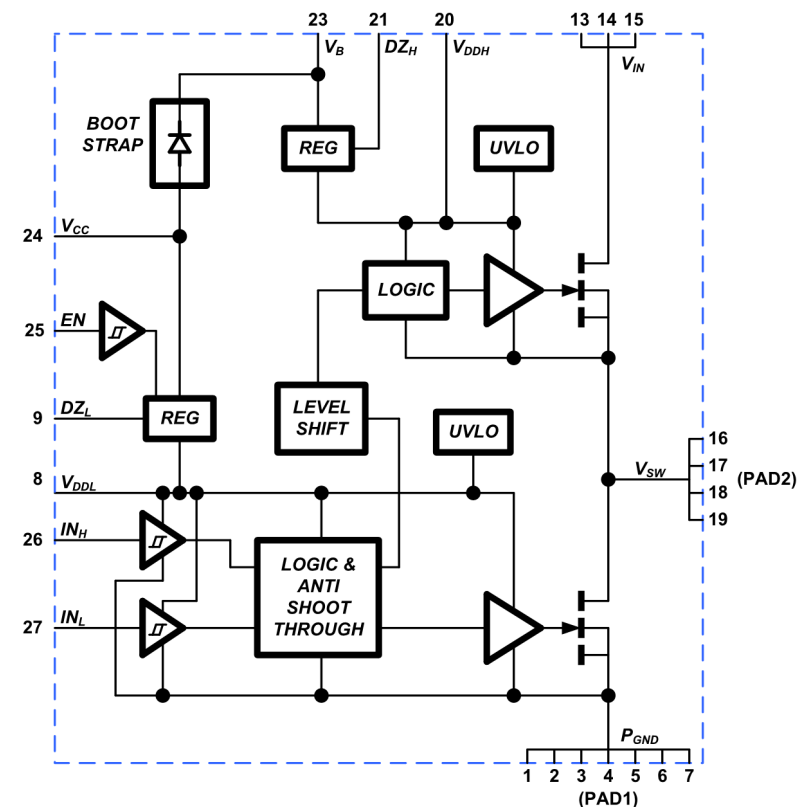
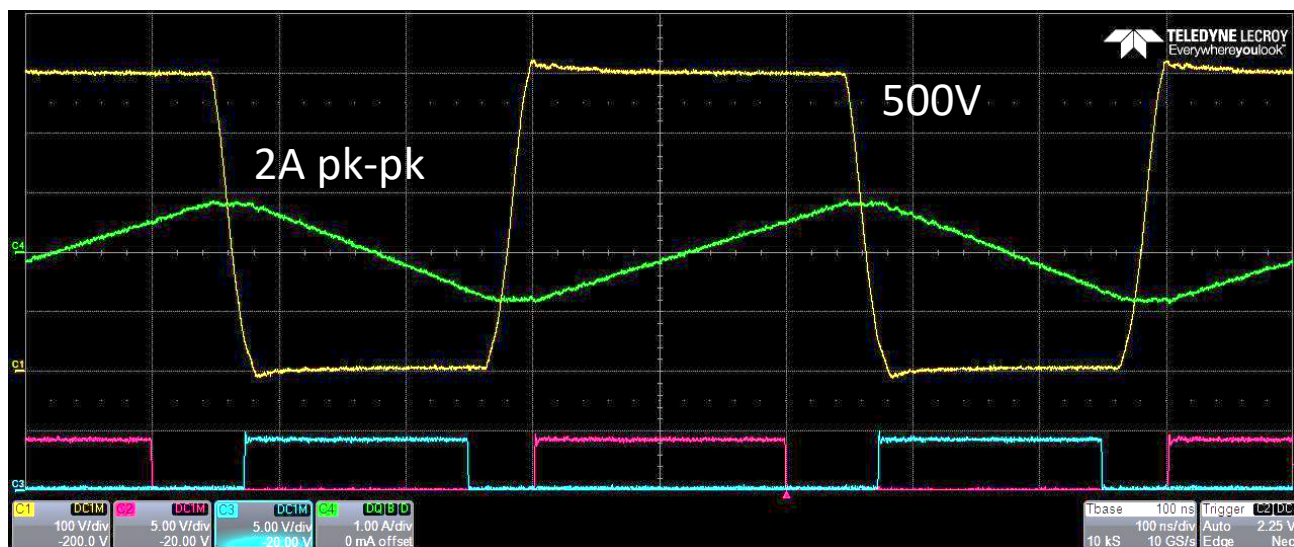




## Monolithic integration at 650V

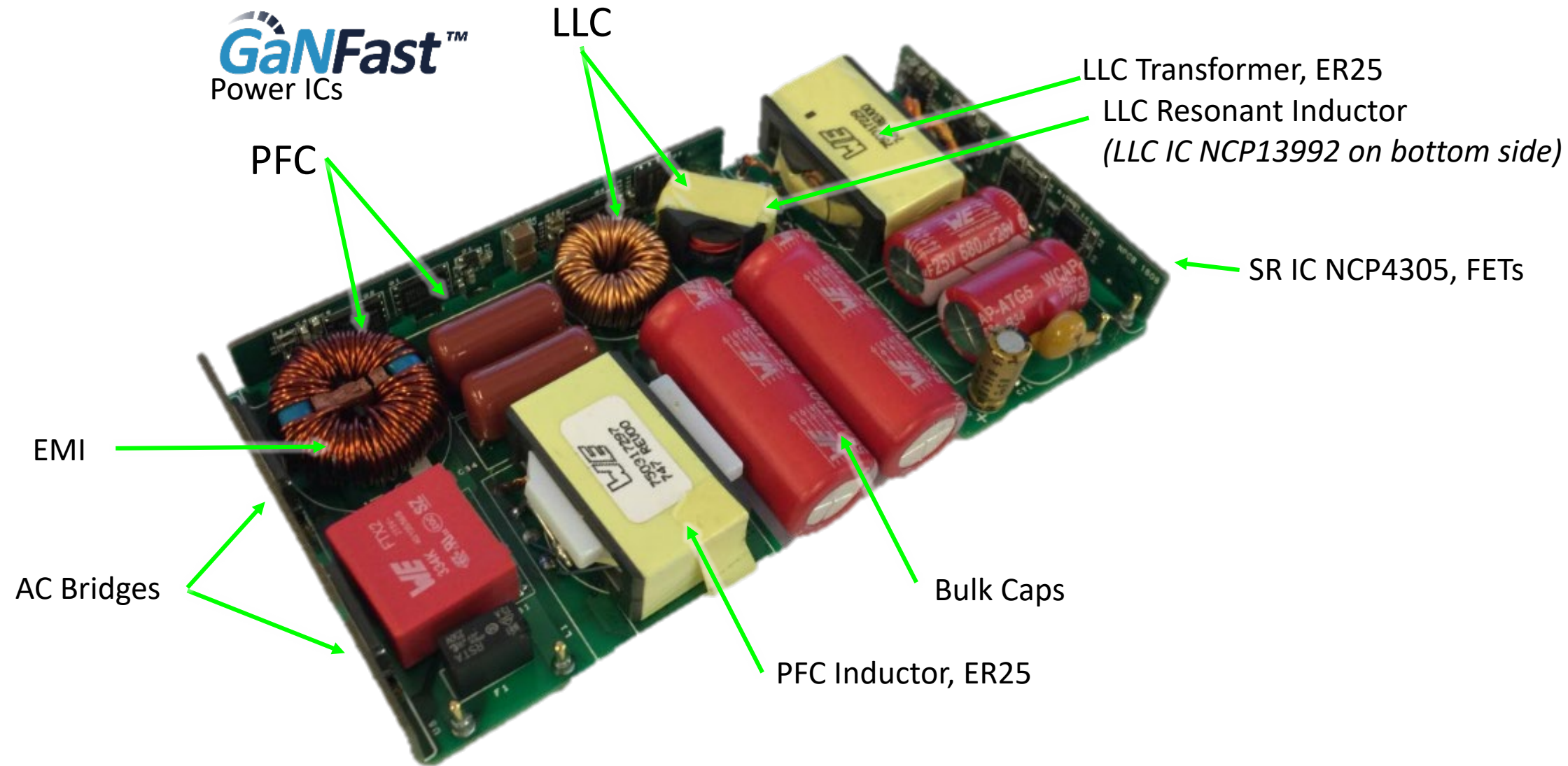
- 2x 650V eMode GaN FETs (*a/symmetrical range 120-600 mΩ*)
- 2x 6V GaN gate drivers
- 2x 30V to 6V GaN regulators and UVLO circuits
- 650V GaN level-shifters and bootstrap drivers
- GaN Logic (shoot-through protection, fault mgmt, ESD, etc...)

## 2 MHz soft-switching operation





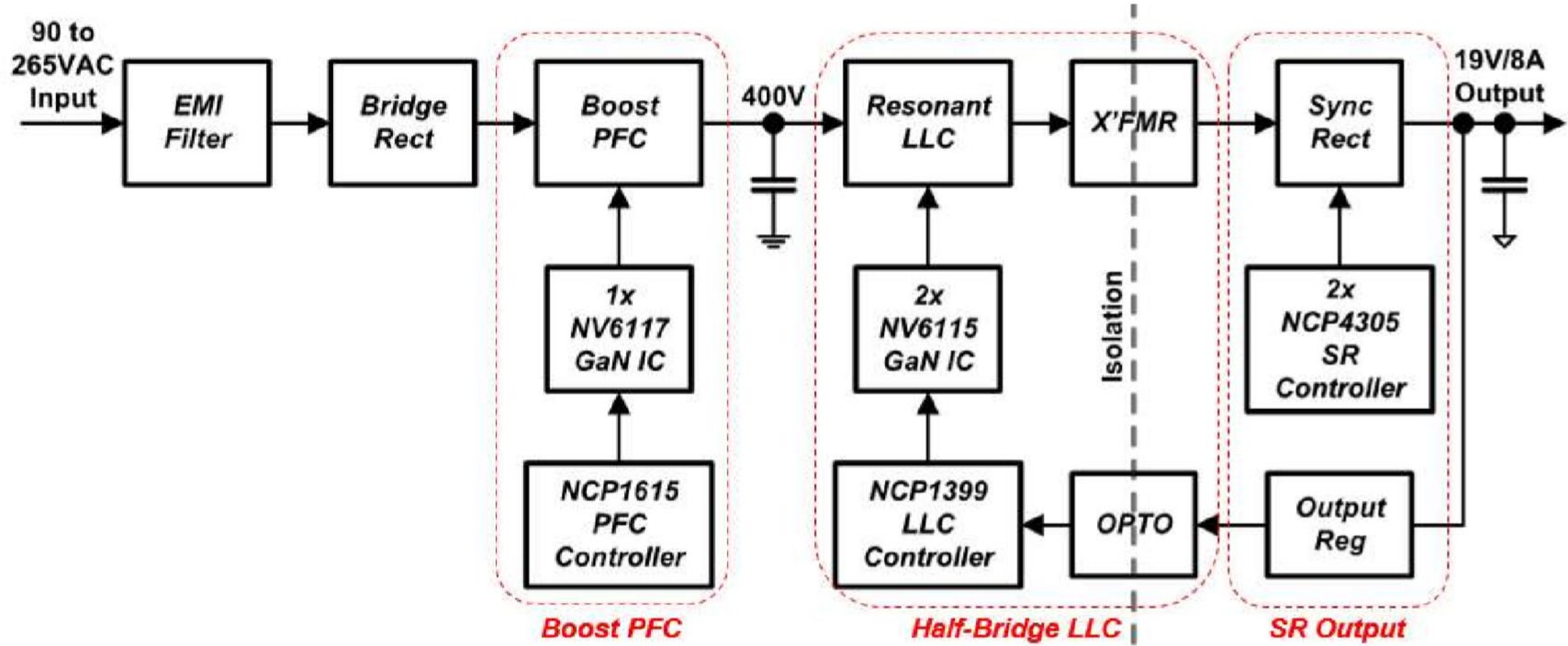
# 150W, 19V: PFC min 200 kHz, LLC 500 kHz







# Block Diagram – 150W/19V





# 500kHz 150W/19V

Ref.	Parameter	Value	Units
V <sub>IN</sub>	Input Voltage	90-265	V <sub>AC</sub>
		47-63	Hz
V <sub>OUT</sub>	Output Voltage	19	V
I <sub>OUT</sub>	Output Current (100% load)	8	A
I <sub>OUT_LIM</sub>	Output Current Limitation (short-circuit or over-load)	9.5	
P <sub>OUT</sub>	Output Power (max)	150	W
F <sub>SW</sub>	Switching Frequency	PFC (120V, 100% load)	200
		PFC (220V, 100% load)	100
		LLC	500
η	Efficiency	230 V <sub>AC</sub> , 150 W	94.9
		115 V <sub>AC</sub> , 150 W	93.8
P <sub>STBY</sub>	Standby Power Consumption	115 V <sub>AC</sub>	< in progress
		230 V <sub>AC</sub>	< in progress
PF	Power Factor	0.95	
	Board Dimensions	100 x 50 x 12.5	mm
	Board Volume (uncased)	62.5	cc
	Power Density (uncased)	39.3	W/in <sup>3</sup>
		2.4	W/cc





# PFC Stage



## Switching Waveforms: CrCM PFC Boost Stage

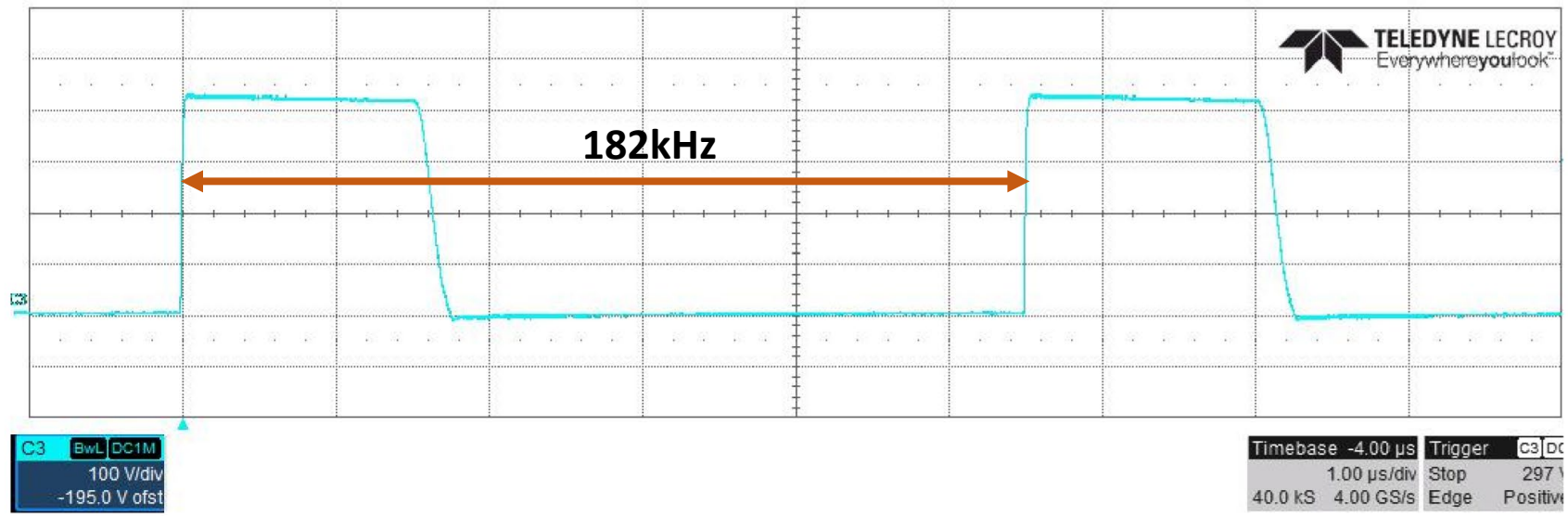
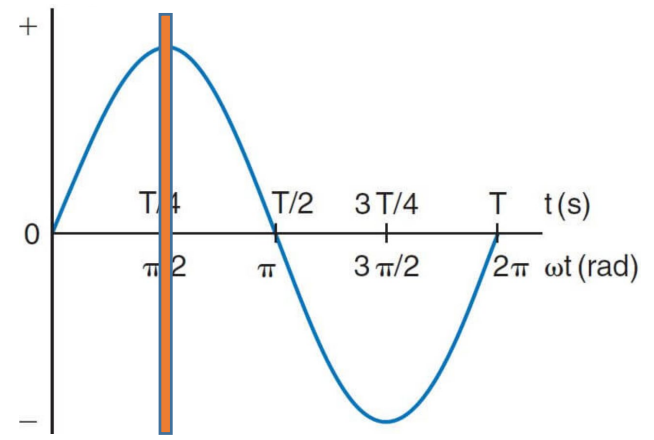


Fig. 8a: CrCM PFC Boost 90 V<sub>IN</sub>, 400 V<sub>OUT</sub>, 150 W, 182 kHz (peak of AC line)







## Switching Waveforms: DC-DC (LLC) Stage

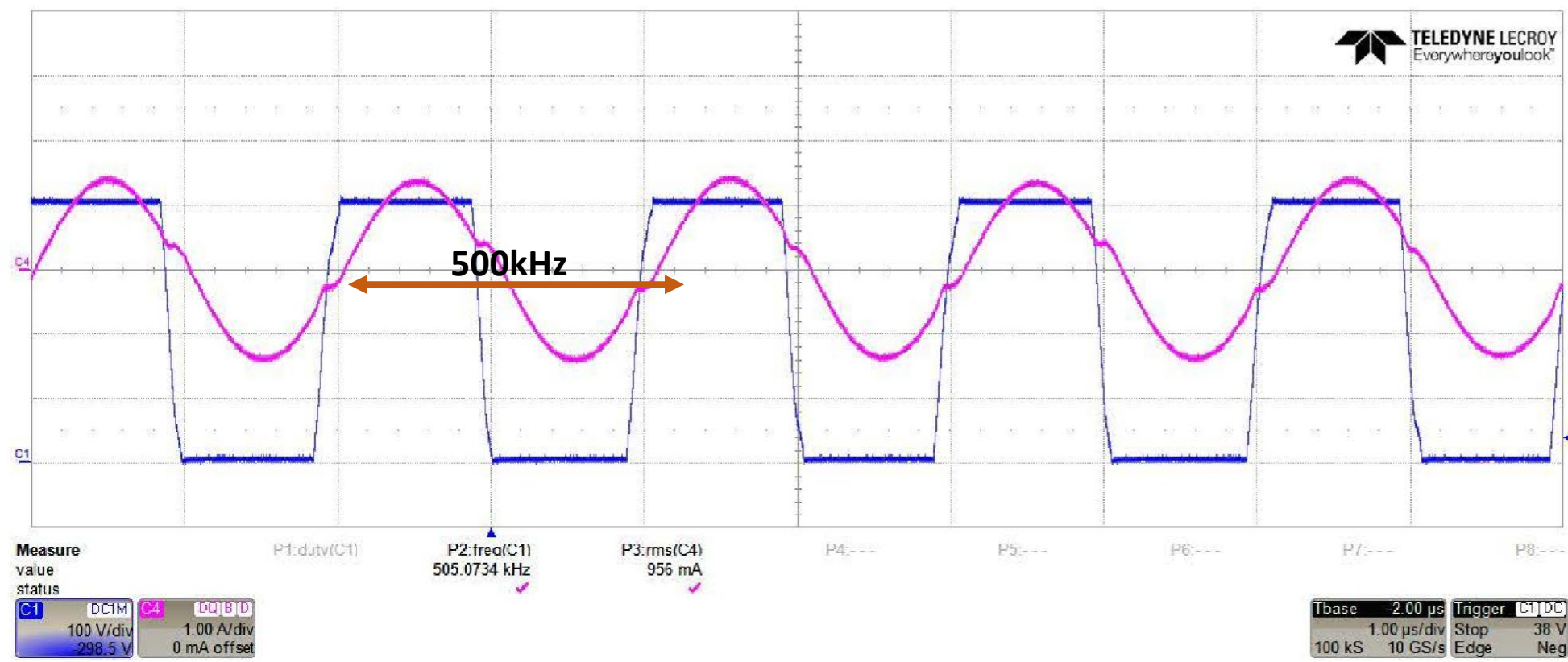
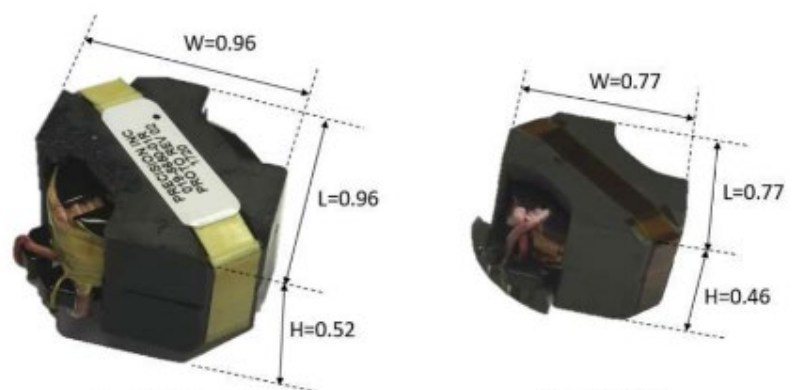


Fig. 9a: LLC  $V_{sw}$ ,  $I_L$ , 19 V<sub>OUT</sub>, 8 A



# Reduced Magnetics Size @ 500kHz



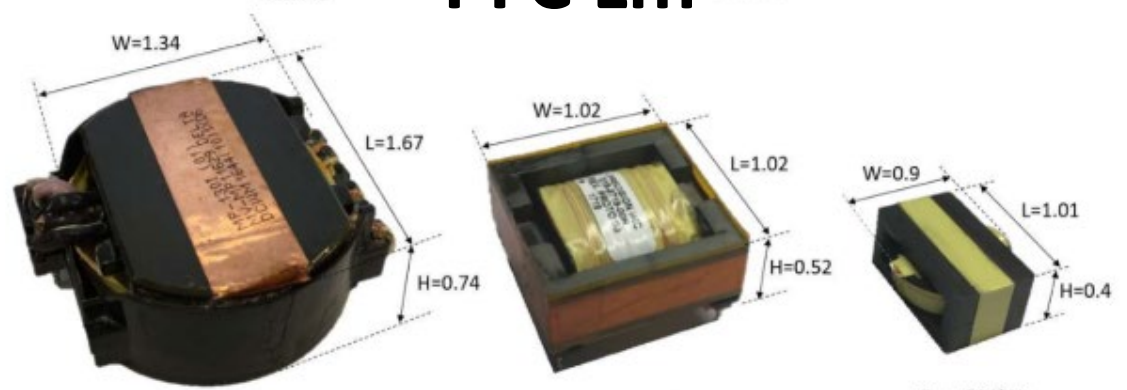
Fsw=100kHz  
RM10/ILP  
0.48 in<sup>3</sup>

Fsw=200kHz  
RM8/ILP  
0.27 in<sup>3</sup>

**PFC Lm**

$$L = \frac{V_{irms}^2 \cdot (V_o - \sqrt{2} \cdot V_{irms})}{2 \cdot f_{sw} \cdot P_i \cdot V_o}$$

Fsw ↑ → Lm ↓ → Size ↓



Fsw=100kHz  
PT40  
1.66 in<sup>3</sup>

Fsw=300kHz  
EFD25  
0.54 in<sup>3</sup>

Fsw=500kHz  
ER25  
0.36 in<sup>3</sup>

**LLC Lm**

Fsw ↑ → Lr, Cr ↓ → Lm ↓ → Size ↓

GaN → Coss ↓





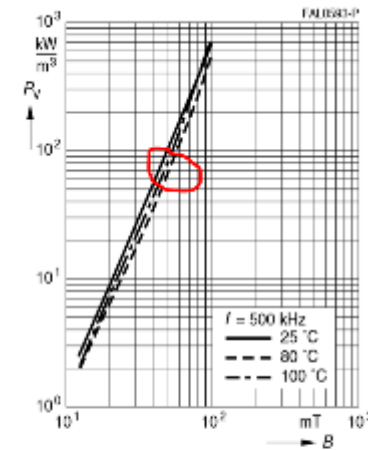
# TDK N49 Core Material (500kHz)



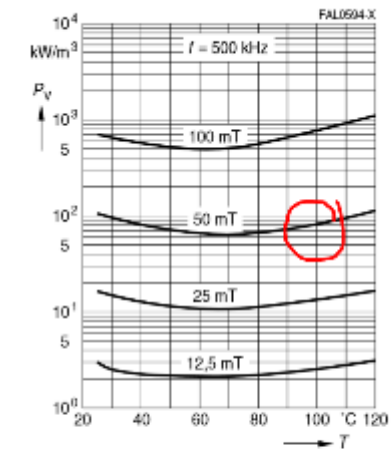
## Material properties

Preferred application	Power transformers		
Material	N49		
Base material	MnZn		
	Symbol	Unit	
Initial permeability (T = 25 °C)	$\mu_i$		1500 +25%
Flux density (H = 1200 A/m, f = 10 kHz)	$B_S$ (25 °C)	mT	490
	$B_S$ (100 °C)	mT	400
Coercive field strength (f = 10 kHz)	$H_c$ (25 °C)	A/m	38
	$H_c$ (100 °C)	A/m	33
Optimum frequency range		kHz	300 ...
			1000
Hysteresis material constant	$\eta_B$	$10^{-6}/\text{mT}$	<0.4
Curie temperature	$T_C$	°C	>240
Mean value of $\alpha_F$ at 25 ... 55 °C		$10^{-6}/\text{K}$	—
Density (typical values)		kg/m <sup>3</sup>	4750
Relative core losses (typical values)	$P_V$		
25 kHz, 200 mT, 100 °C		kW/m <sup>3</sup>	—
100 kHz, 200 mT, 100 °C		kW/m <sup>3</sup>	—
300 kHz, 100 mT, 100 °C		kW/m <sup>3</sup>	330
500 kHz, 50 mT, 100 °C		kW/m <sup>3</sup>	80
1 MHz, 50 mT, 100 °C	kW/m <sup>3</sup>	475	
Resistivity	$\rho$	$\Omega\text{m}$	17
Core shapes	RM, EFD, ELP, Toroid, EQ, ER		

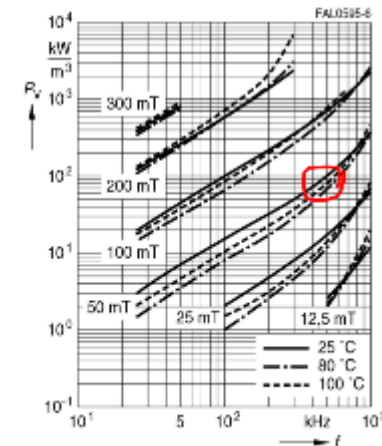
versus AC field flux density (measured on R34 toroids)



versus temperature (measured on R34 toroids)



Relative core losses versus frequency (measured on R34 toroids)

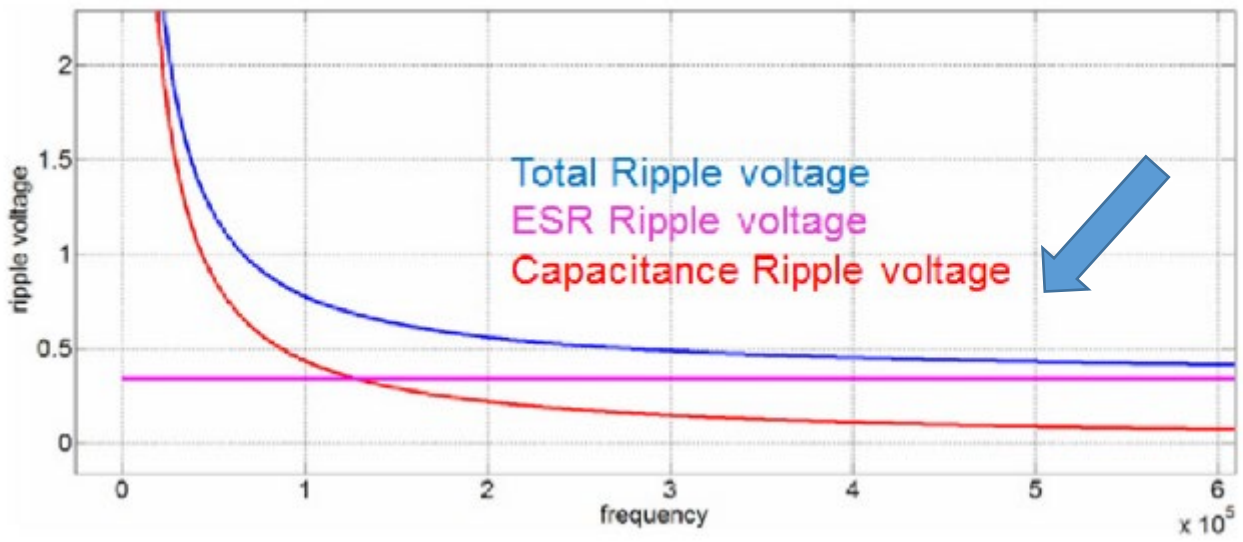






# Reduced Output Cap @ 500kHz

Ripple voltage vs Switching Frequency

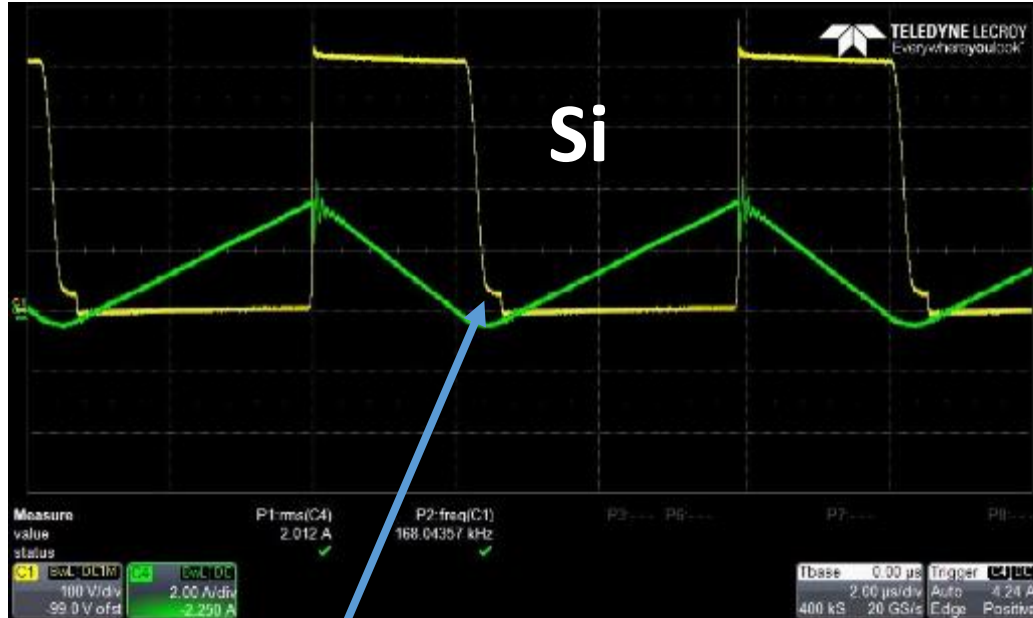


- Output ripple = ESR ripple ( $I_o, ESR$ ) + Cap ripple ( $C_o, I_o, f_{sw}$  dependent)
- ESR is dominant factor for output ripple at high fsw
- Small output cap is used for high fsw

“Design Considerations of Resonant Network and Transformer Magnetics for High Frequency LLC Resonant Converter”, J Electr Eng Technol. 2016; 11(2): 383-392

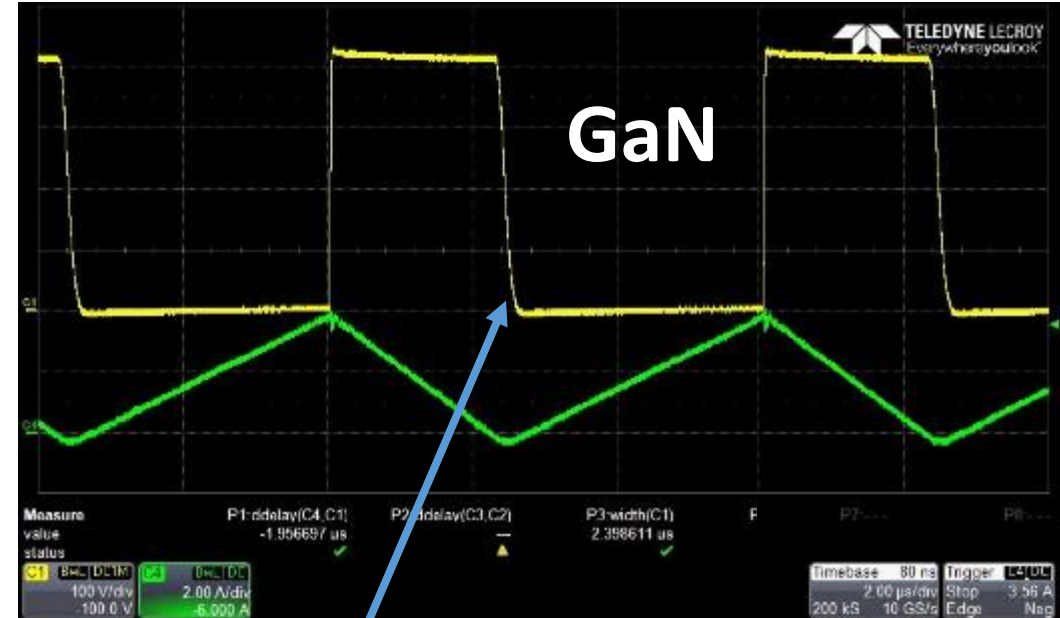


# GaN Increases Efficiency



120V<sub>AC</sub> Si CP partial hard-switching (~200kHz)

- Si C<sub>OSS</sub> is 50x-100x worse than GaN at V<sub>DS</sub> < 30V
- High loss due to large stored charge while hard-switching



120V<sub>AC</sub> GaN clean ZVS waveforms (~200kHz)



- Turn-off losses low due to integrated drive
- Near loss-less ZVS turn-on transition
- Minimize deadtime for low reverse conduction loss
- No voltage spikes / overshoot





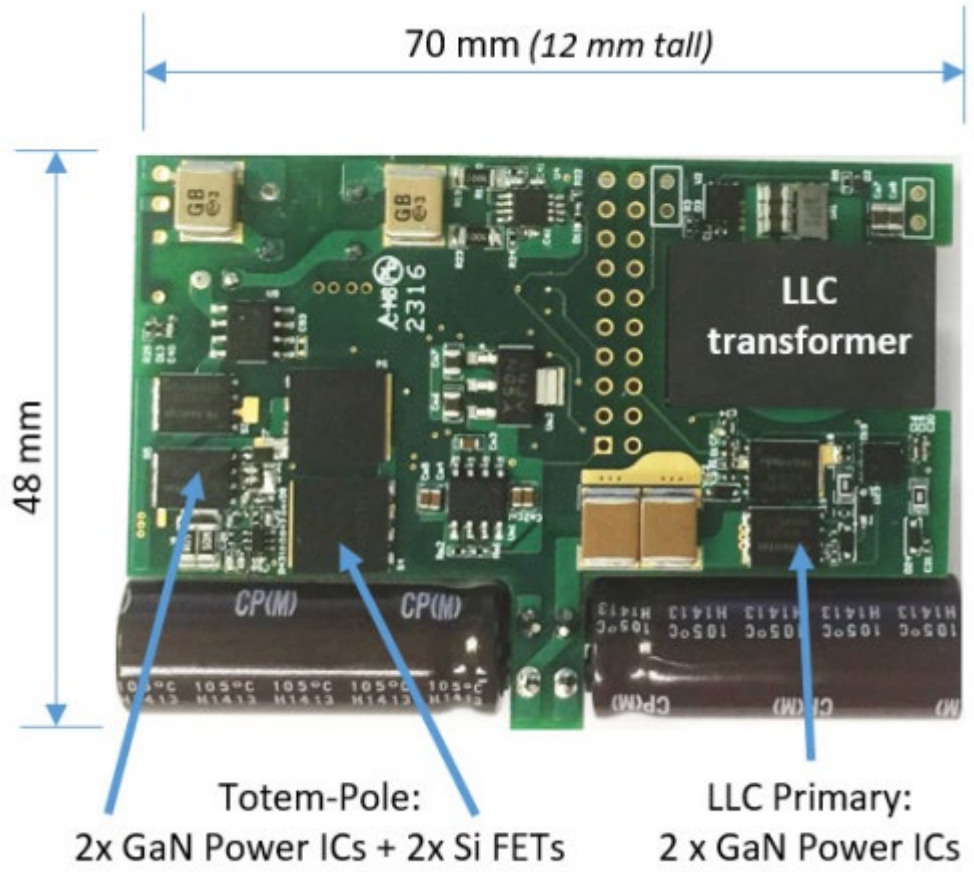
# 93% Efficiency @ 90VAC, Full Load



ITEM	Existing Silicon 140W Design	GaNFast 150W Design (NEV031)
Picture		
Spec	140W (19V / 7.37A)	150W(19V/7.9A)
Power Device	Si	Navitas GaNFast IC
PCB Size	60 x 149.5 x 31	50 x 100 x 12.5
Case Size	68 x 156 x 39 (414cc)	126cc (estimated)
Efficiency	89%	93%
PWM frequency	PFC= 40kHz, LLC= 85kHz	PFC= 200kHz, LLC = 500kHz



# Next Generation 1MHz 150W NB Adaptor



## 150 W, 1 MHz Design

**Topology:** Totem-Pole PFC + LLC at 1 MHz  
**Power Device:** GaNFast power ICs  
**Efficiency:** >95% peak efficiency at full load



*Let's go* **GaNFast™**